

NCE N-Channel Super Trench Power MOSFET

Description

The NCEP85T12D uses **Super Trench** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{DS(ON)}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

General Features

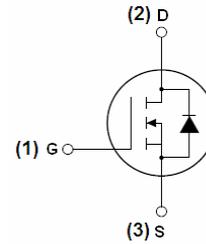
- $V_{DS} = 85V, I_D = 120A$
 $R_{DS(ON)} < 5.5m\Omega @ V_{GS} = 10V$
- Excellent gate charge x $R_{DS(on)}$ product(FOM)
- Very low on-resistance $R_{DS(on)}$
- 175 °C operating temperature
- Pb-free lead plating
- 100% UIS tested

Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

100% UIS TESTED!

100% ΔV_{ds} TESTED!



Schematic diagram



Marking and pin assignment



TO-263-2L top view

Package Marking and Ordering Information

| Device Marking | Device | Device Package | Reel Size | Tape width | Quantity |
|----------------|------------|----------------|-----------|------------|----------|
| NCEP85T12D | NCEP85T12D | TO-263-2L | - | - | - |

Absolute Maximum Ratings ($T_C = 25^\circ C$ unless otherwise noted)

| Parameter | Symbol | Limit | Unit |
|---|--------------------|------------|---------------|
| Drain-Source Voltage | V_{DS} | 85 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Drain Current-Continuous | I_D | 120 | A |
| Drain Current-Continuous($T_C = 100^\circ C$) | $I_D(100^\circ C)$ | 88 | A |
| Pulsed Drain Current | I_{DM} | 320 | A |
| Maximum Power Dissipation | P_D | 160 | W |
| Derating factor | | 1.1 | W/ $^\circ C$ |
| Single pulse avalanche energy ^(Note 5) | E_{AS} | 784 | mJ |
| Operating Junction and Storage Temperature Range | T_J, T_{STG} | -55 To 175 | $^\circ C$ |

Thermal Characteristic

| | | | |
|--|-----------------|------|----------------------|
| Thermal Resistance, Junction-to-Case ^(Note 2) | $R_{\theta JC}$ | 0.94 | $^{\circ}\text{C/W}$ |
|--|-----------------|------|----------------------|

Electrical Characteristics ($T_C=25^{\circ}\text{C}$ unless otherwise noted)

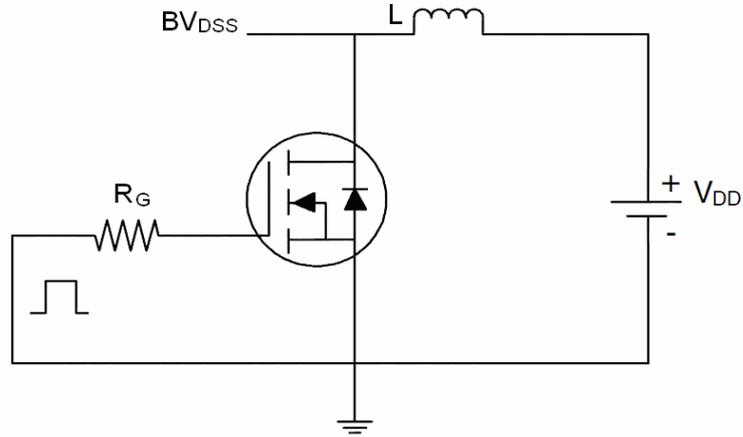
| Parameter | Symbol | Condition | Min | Typ | Max | Unit |
|--|--------------|---|-----|------|-----------|------------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{GS}=0V, I_D=250\mu A$ | 85 | | - | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS}=85V, V_{GS}=0V$ | - | - | 1 | μA |
| Gate-Body Leakage Current | I_{GSS} | $V_{GS}=\pm 20V, V_{DS}=0V$ | - | - | ± 100 | nA |
| On Characteristics ^(Note 3) | | | | | | |
| Gate Threshold Voltage | $V_{GS(th)}$ | $V_{DS}=V_{GS}, I_D=250\mu A$ | 2.5 | 3.3 | 4.5 | V |
| Drain-Source On-State Resistance | $R_{DS(ON)}$ | $V_{GS}=10V, I_D=60A$ | - | - | 5.5 | m Ω |
| Forward Transconductance | g_{FS} | $V_{DS}=10V, I_D=60A$ | 40 | - | - | S |
| Dynamic Characteristics ^(Note 4) | | | | | | |
| Input Capacitance | C_{iss} | $V_{DS}=40V, V_{GS}=0V,$ $F=1.0\text{MHz}$ | - | 4300 | - | PF |
| Output Capacitance | C_{oss} | | - | 830 | - | PF |
| Reverse Transfer Capacitance | C_{rss} | | - | 57 | - | PF |
| Switching Characteristics ^(Note 4) | | | | | | |
| Turn-on Delay Time | $t_{d(on)}$ | $V_{DD}=40V, I_D=60A$ $V_{GS}=10V, R_G=4.7\Omega$ | - | 13.5 | - | nS |
| Turn-on Rise Time | t_r | | - | 12.5 | - | nS |
| Turn-Off Delay Time | $t_{d(off)}$ | | - | 38 | - | nS |
| Turn-Off Fall Time | t_f | | - | 13.5 | - | nS |
| Total Gate Charge | Q_g | $V_{DS}=40V, I_D=60A,$ $V_{GS}=10V$ | - | 55 | | nC |
| Gate-Source Charge | Q_{gs} | | - | 21 | | nC |
| Gate-Drain Charge | Q_{gd} | | - | 9 | | nC |
| Drain-Source Diode Characteristics | | | | | | |
| Diode Forward Voltage ^(Note 3) | V_{SD} | $V_{GS}=0V, I_S=120A$ | - | | 1.2 | V |
| Diode Forward Current ^(Note 2) | I_S | | - | - | 120 | A |
| Reverse Recovery Time | t_{rr} | $T_J = 25^{\circ}\text{C}, I_F = I_S$ $di/dt = 100A/\mu\text{s}$ ^(Note 3) | - | 74 | | nS |
| Reverse Recovery Charge | Q_{rr} | | - | 176 | | nC |

Notes:

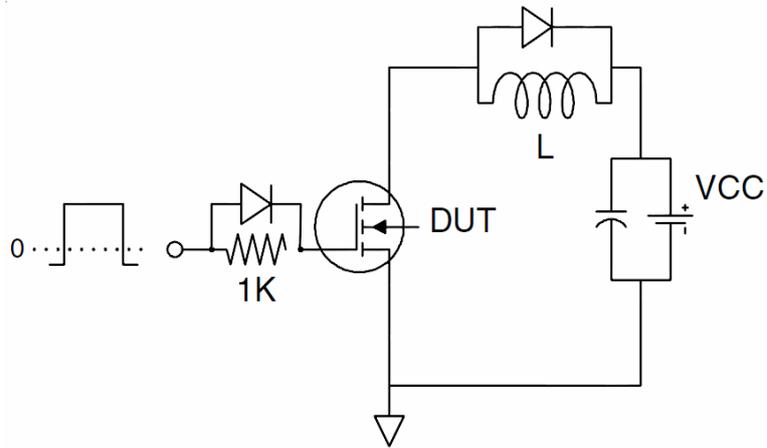
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production
5. EAS condition : $T_J=25^{\circ}\text{C}, V_{DD}=42.5V, V_G=10V, L=0.5\text{mH}, R_G=25\Omega$

Test Circuit

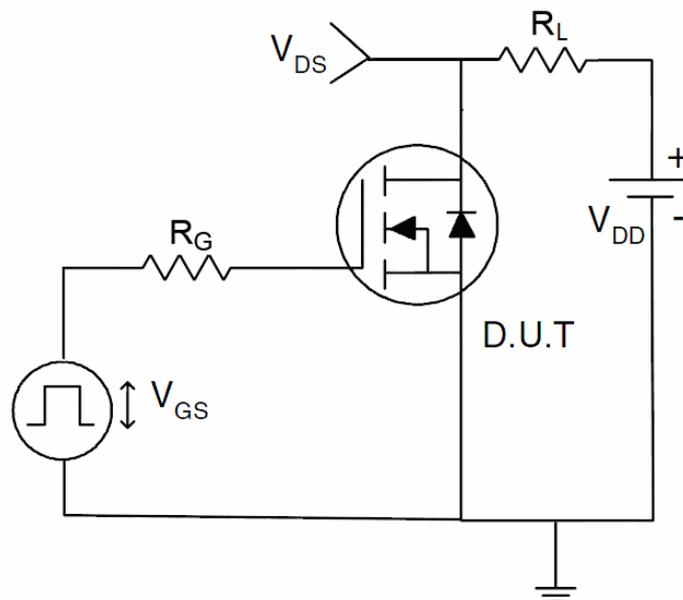
1) E_{AS} test Circuit



2) Gate charge test Circuit



3) Switch Time Test Circuit



Typical Electrical and Thermal Characteristics

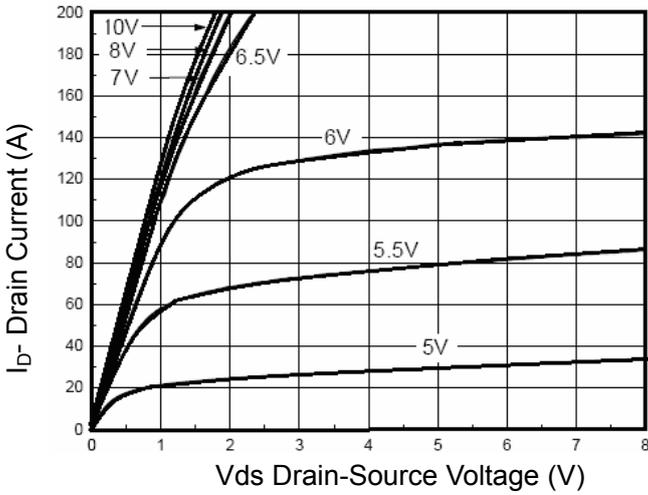


Figure 1 Output Characteristics

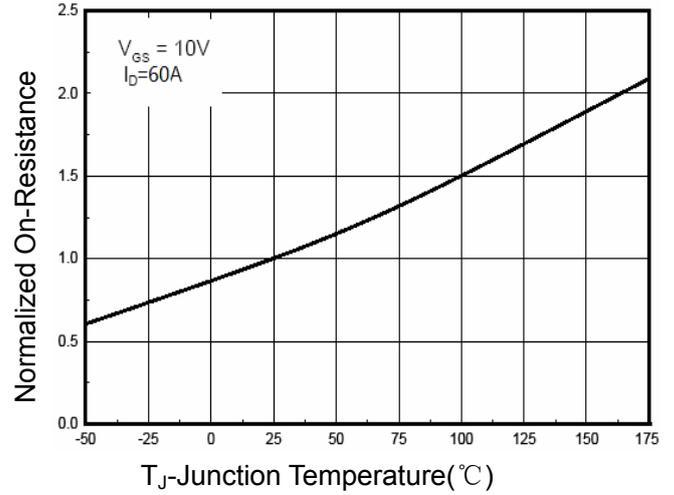


Figure 4 R_{dson} -Junction Temperature

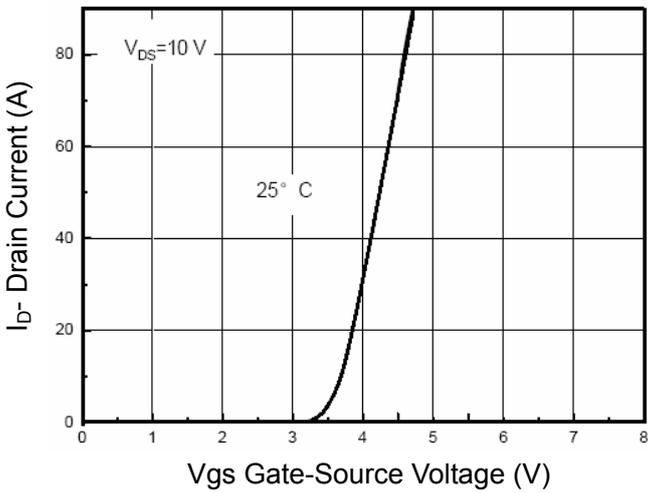


Figure 2 Transfer Characteristics

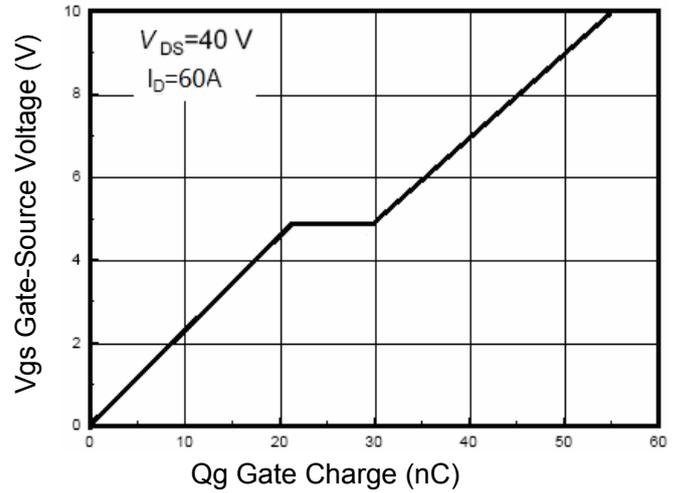


Figure 5 Gate Charge

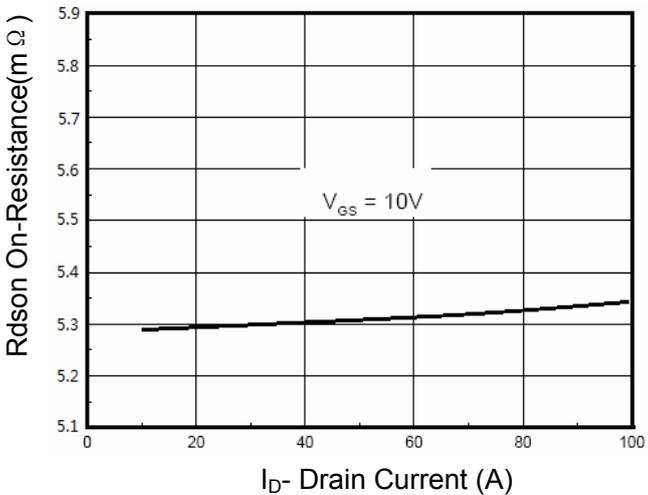


Figure 3 R_{dson} - Drain Current

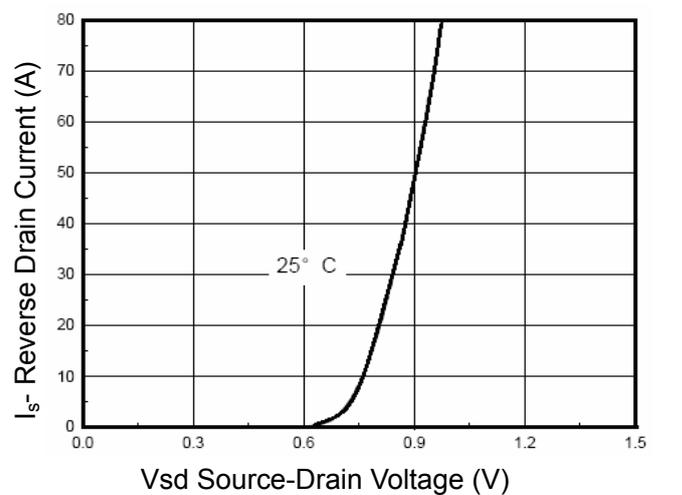


Figure 6 Source- Drain Diode Forward

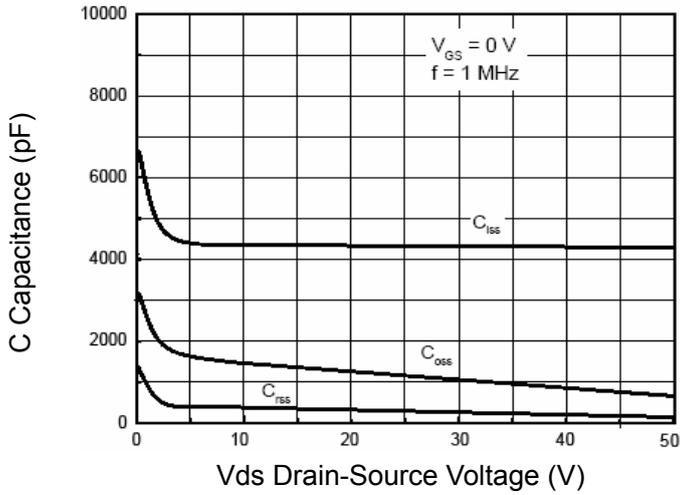


Figure 7 Capacitance vs Vds

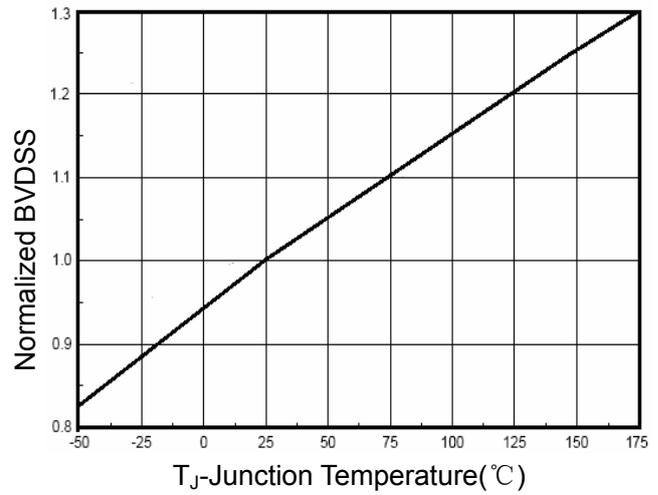


Figure 9 BV_{DSS} vs Junction Temperature

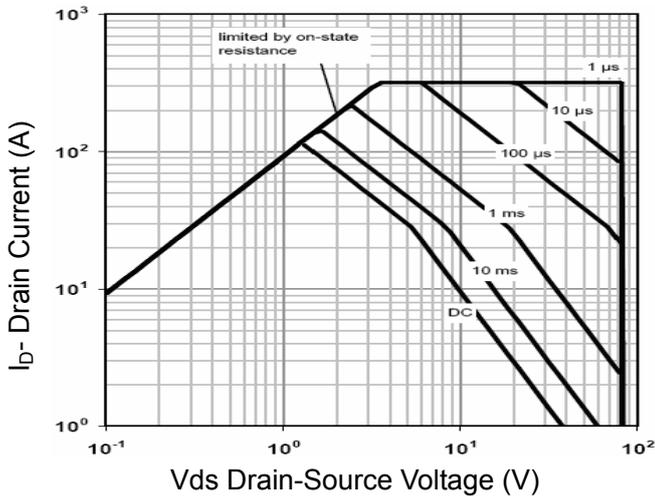


Figure 8 Safe Operation Area

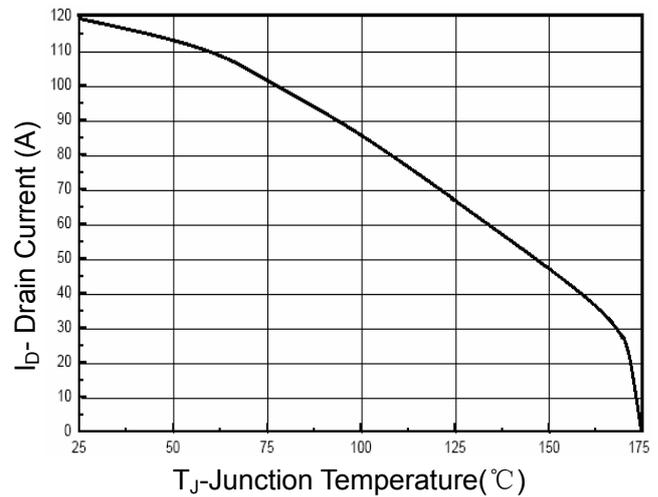


Figure 10 Current De-rating

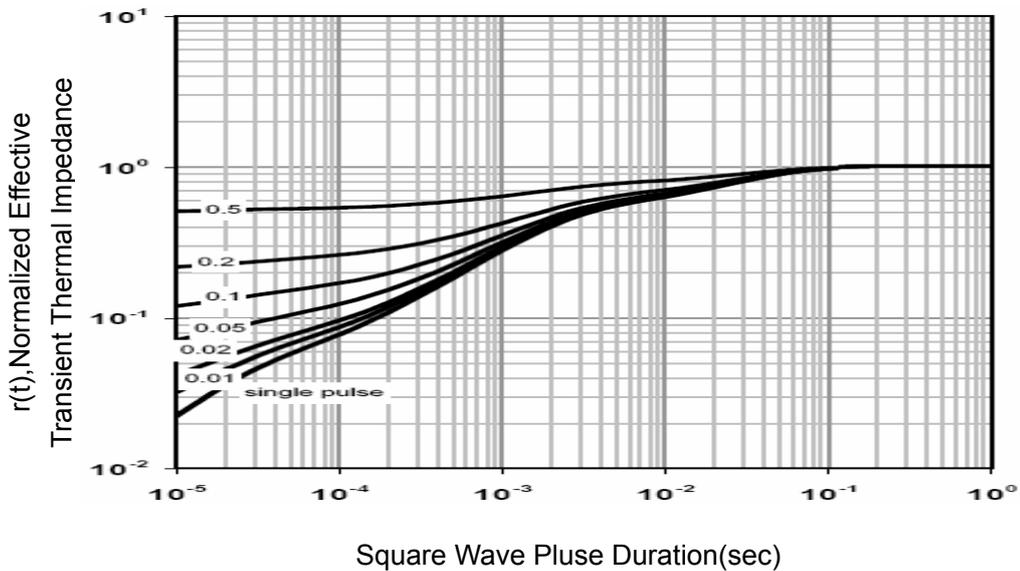
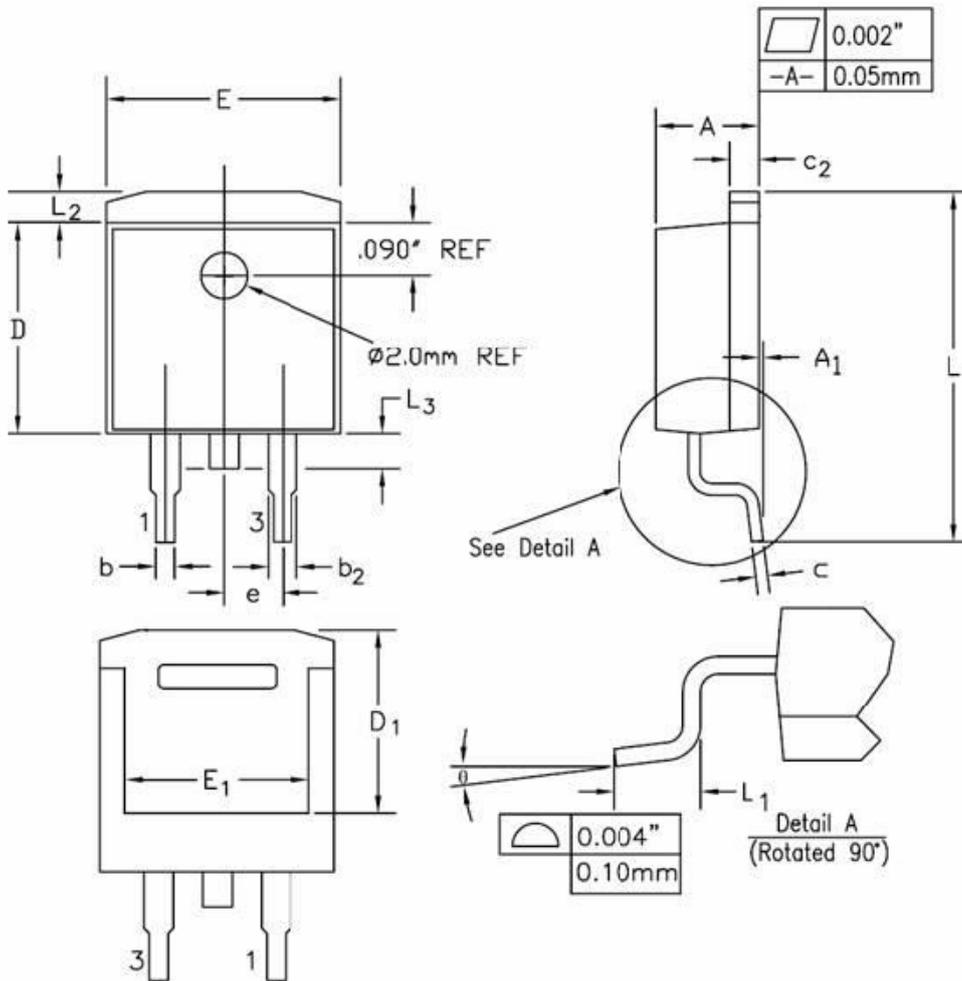


Figure 11 Normalized Maximum Transient Thermal Impedance

TO-263-2L Package Information



| SYMBOL | INCHES | | MILLIMETERS | | NOTES |
|----------|------------|-------|-------------|-------|-------|
| | MIN | MAX | MIN | MAX | |
| A | 0.170 | 0.180 | 4.32 | 4.57 | |
| A1 | - | 0.010 | - | 0.25 | |
| b | 0.028 | 0.037 | 0.71 | 0.94 | |
| b2 | 0.045 | 0.055 | 1.15 | 1.40 | |
| c | 0.018 | 0.024 | 0.46 | 0.61 | |
| c2 | 0.048 | 0.055 | 1.22 | 1.40 | |
| D | 0.350 | 0.370 | 8.89 | 9.40 | |
| D1 | 0.315 | 0.324 | 8.01 | 8.23 | |
| E | 0.395 | 0.405 | 10.04 | 10.28 | |
| E1 | 0.310 | 0.318 | 7.88 | 8.08 | |
| e | 0.100 BSC. | | 2.54 BSC. | | |
| L | 0.580 | 0.620 | 14.73 | 15.75 | |
| L1 | 0.090 | 0.110 | 2.29 | 2.79 | |
| L2 | 0.045 | 0.055 | 1.15 | 1.39 | |
| L3 | 0.050 | 0.070 | 1.27 | 1.77 | |
| θ | 0° | 8° | 0° | 8° | |

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